

| External_Type  | Material_Group  | Substances   | CAS_Number      | Mass          | Mass_Percentage_in_Leaf | Massmg         |
|----------------|-----------------|--|-----------------|---------------|-------------------------|----------------|
| Wire           | Pure metal      | Aluminium (Al)   | 7429-90-5       | 0.01          | 100.0                   | 0.26           |
|                |                 |  | <b>Subtotal</b> | <b>0.01</b>   | <b>100</b>              | <b>0.26</b>    |
| Die            | Doped silicon   | Silicon (Si)   | 7440-21-3       | 0.32          | 100.0                   | 6.3            |
|                |                 |  | <b>Subtotal</b> | <b>0.32</b>   | <b>100</b>              | <b>6.3</b>     |
| Solder Wire    | Lead alloy      | Tin (Sn)   | 7440-31-5       | 0             | 5.0                     | 0.05           |
|                | Lead alloy      | Silver (Ag)  | 7440-22-4       | 0             | 2.5                     | 0.03           |
|                | Lead alloy      | Lead (Pb)  | 7439-92-1       | 0.05          | 92.5                    | 0.93           |
|                |                 |  | <b>Subtotal</b> | <b>0.05</b>   | <b>100</b>              | <b>1.01</b>    |
| Wire           | Pure metal      | Aluminium (Al)   | 7429-90-5       | 0.2           | 100.0                   | 4              |
|                |                 |  | <b>Subtotal</b> | <b>0.2</b>    | <b>100</b>              | <b>4</b>       |
| Lead Frame     | Copper alloy    | Phosphorous (P)  | 7723-14-0       | 0.02          | 0.03                    | 0.4            |
|                | Copper alloy    | Iron (Fe)  | 7439-89-6       | 0.04          | 0.06                    | 0.8            |
|                | Copper alloy    | Copper (Cu)  | 7440-50-8       | 67.17         | 99.91                   | 1338.79        |
|                |                 |  | <b>Subtotal</b> | <b>67.23</b>  | <b>100</b>              | <b>1339.99</b> |
| Post-plating   | Pure metal      | Tin (Sn)   | 7440-31-5       | 1.04          | 100.0                   | 20.68          |
|                |                 |  | <b>Subtotal</b> | <b>1.04</b>   | <b>100</b>              | <b>20.68</b>   |
| Mould Compound |                 | Tetrabromobisphenol A/Epichlorohydrin polymer          | 40039-93-8      | 0.22          | 0.7                     | 4.35           |
|                | Polymer         | Phenol Formaldehyde resin (generic)                    | 9003-35-4       | 1.87          | 6.0                     | 37.26          |
|                | Polymer         | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3      | 3.74          | 12.0                    | 74.52          |
|                | Filler          | Silica fused   | 60676-86-0      | 21.81         | 70.0                    | 434.7          |
|                | Carbon Black    | Carbon black   | 1333-86-4       | 0.09          | 0.3                     | 1.86           |
|                | Filler          | Misc. Silica compounds (generic)                       | 14808-60-7      | 3.12          | 10.0                    | 62.1           |
|                | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4          | 1309-64-4       | 0.31          | 1.0                     | 6.21           |
|                |                 |  | <b>Subtotal</b> | <b>31.16</b>  | <b>100</b>              | <b>621</b>     |
|                |                 |  | <b>Total</b>    | <b>100.01</b> | <b>100</b>              | <b>1993.24</b> |

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